

# Specification of Thermoelectric Module

## TES2-127-63-02

### Description

The TES2-127-63-02 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 127-63 couples module in size of 29.8 mm × 29.8 mm (top)/14.8 mm×29.8 mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

### Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

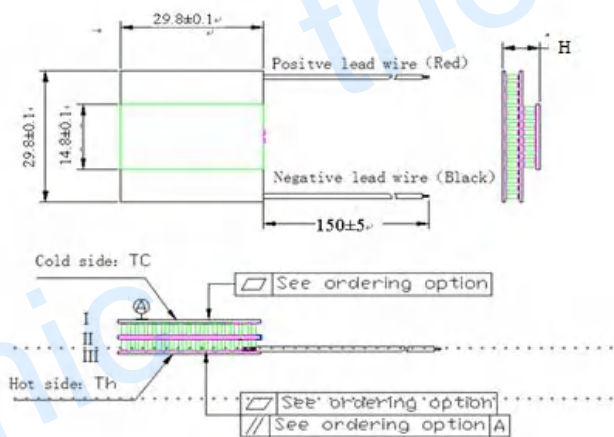
### Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

### Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	93	104	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	14.6	16.4	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (Amps)	1.6	1.6	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	9.5	10.5	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (Ohms)	7.4	8.45	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



### Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 7.75±0.2	0: 0.07/0.07	150±5/Specify
TF	1: 7.75±0.1	1: 0.025/0.025	150±5/Specify

Eg. TF00: Thickness 7.75±0.2(mm) and Flatness/ Parallelism: 0.07/0.07(mm)

### Manufacturing Options

#### A. Solder:

1. T100: BiSn (T<sub>melt</sub>=138°C)
2. T200: CuAgSn (T<sub>melt</sub> = 217°C)
3. T240: SbSn (T<sub>melt</sub> = 240°C)

#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

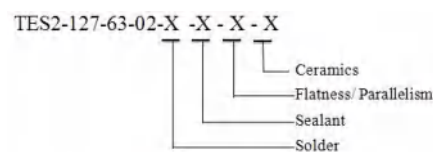
#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

### Naming for the Module

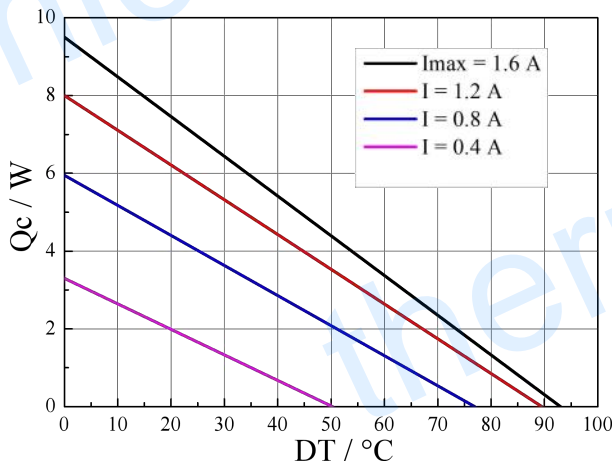


TES2-127-63-02-T100 - NS - TF00 - AlO  
 T100: Solder, BiSn (Melting Point=138 °C)  
 NS: No sealing                      AlO: Alumina white 96%  
 TF01: Thickness ±0.3(mm) and Flatness/Parallelism 0.1/0.1mm)

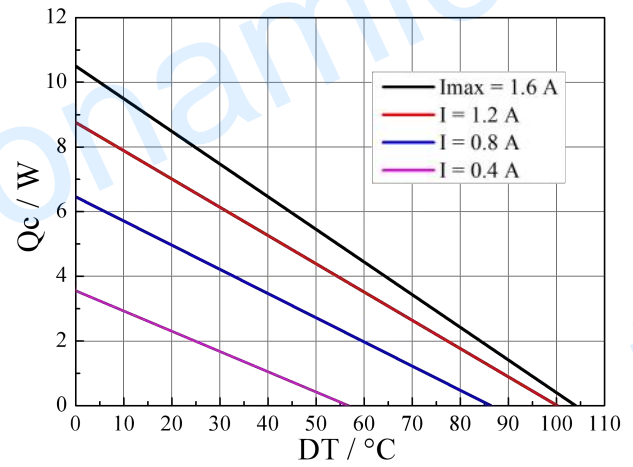
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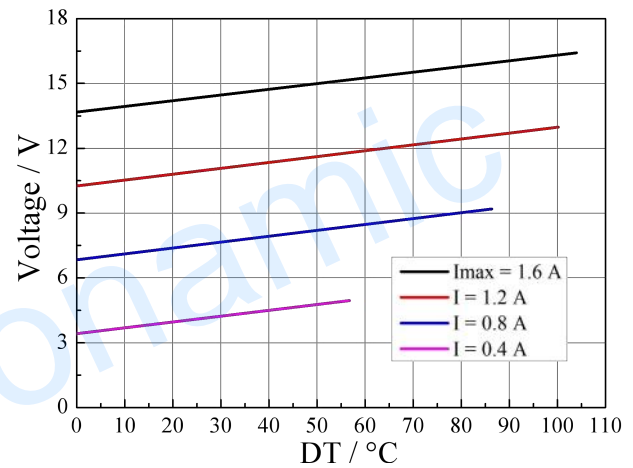
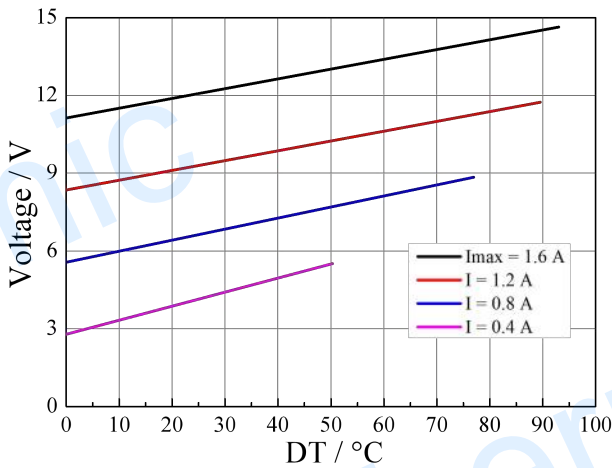
### Performance Curves at $T_h=27\text{ }^\circ\text{C}$



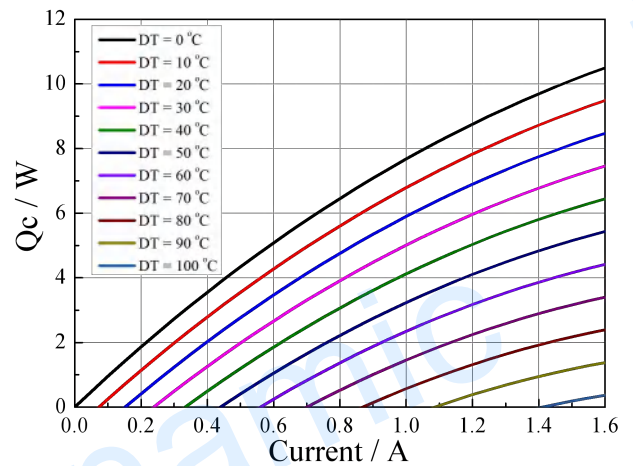
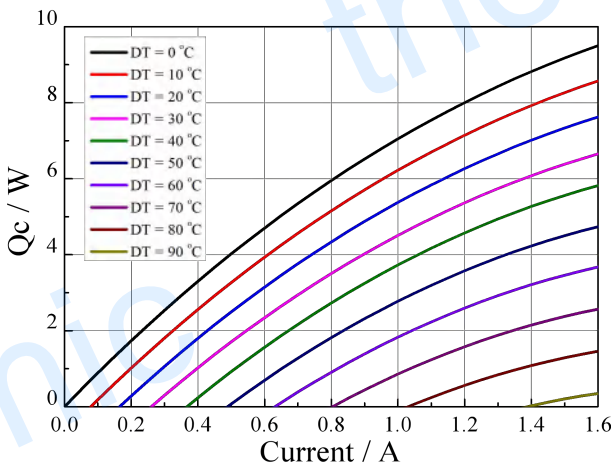
### Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$



Standard Performance Graph  $Q_c = f(I)$

### Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below  $100\text{ }^\circ\text{C}$

- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC